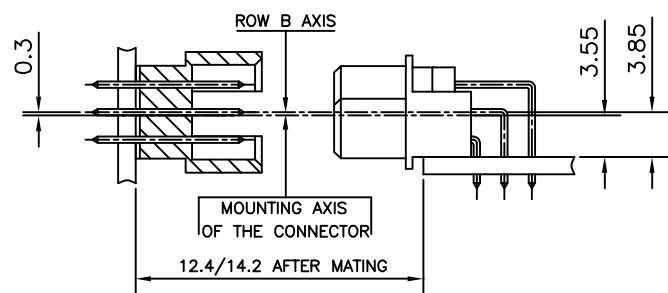


25	18.2 ^{+0.5} _{-0.2}
15	13.1 ^{+0.5} _{-0.2}
TERM. STYLE	L



TECHNICAL SPECIFICATION

HOUSING MATERIAL : THERMOPLASTIC POLYESTER UL94V0, GREY
 HOUSING CAN WITHSTAND EXPOSURE TO LEAD FREE WAVE SOLDERING TEMPERATURE OF 260-265°C FOR STRAIGHT CONNECTORS AS IT IS IN CLASSICAL LEAD WAVE SOLDERING AT 235-250°C

CONTACT MATERIAL : COPPER ALLOY
 CONTACT ACTIVE ZONE PLATING : GOLD OVER NICKEL

CONTACT TERMINATION ZONE PLATING

TIN LEAD VERSION : TIN LEAD OVER NICKEL
 LEAD FREE VERSION : TIN (PURE MATTE) OVER NI

ELECTRICAL DATA

CURRENT RATING AT 20°C : 1.5 A
 CURRENT (I MAX) : 2 A
 TEMPERATURE RANGE : -55°C/+125°C
 CONTACT RESISTANCE : ≤ 20mΩ
 INSULATION RESISTANCE : ≥ 10⁶ MΩ
 TEST VOLTAGE (rms) : 1000V

MECHANICAL DATA

INSERTION FORCE PER CONTACT : ≤ 0.94N
 EXTRACTION FORCE PER CONTACT : ≥ 0.15N
 REFERENCE SPECIFICATIONS : DIN 41612 / IEC 603-2

SERIES	8609	3	48	7	6	15	7	6	5	000E
ROWS FITTED WITH CONTACTS										
Rows a - c	4	32								
Rows a b c	3	48								
NUMBER OF CONTACTS										
TYPE OF INSULATOR										
3 ROW MALE INSULATOR	7									
METHOD OF MOUNTING										
REVERSE MOUNTING -STYLE R/2	6									
TERMINATION										
WIRE WRAP (L = 18.2 ^{+0.5} _{-0.2})	25									
WIRE WRAP (L = 13.1 ^{+0.5} _{-0.2})	15									
OPTIONS										
NO OPTION	7									
PERFORMANCE CLASS										
DIN 41612 CLASS 3	4									
DIN 41612 CLASS 2	5									
DIN 41612 CLASS 1	6									
AS PER MIL C 55302/ JSS 50808	8									
PITCH PER ROW										
2.54	5									
000E	TIN LEAD VERSION									
ELF	LEAD FREE VERSION									

mat'l. code		surface		tolerance		projection		product family	
-		ISO 1302		ISO 406 ISO 1101		mm		8609	
ltr		ecn no		dr		date		title	
A		I04-0063		MINI		17/09/2004		DIN REVERSE HEADER	
B		I05-0089		MINI		19/05/2005		WIRE WRAP DIN 41612 STYLE-R/2	
C		I05-0174		MINI		27/09/2005		scale -	
D		I06-0061		MINI		31/05/2006		dwg no	
				engr		MINI K VANDANATH		sheet 1 of 1	
				chr		17/09/2004		size	
				appd		31/05/2006		A3	
								type	
								Product Customer Drawing	
sheet index		revision		D					
		sheet		1					

NOTES:-

- THE "LF" PRODUCTS MEET EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 3.5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6 MM MINIMUM THICK CIRCUIT BOARD
- LEAD FREE OR RoHS DIRECTIVE LABELING TO BE PROVIDED AS PER GS-14-920 FOR LEAD FREE VERSION.



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